ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.					This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1						Form Type Distribute										
Supplier Information																
Company	Company name* Company				npany unique ID			Unique ID Authority				Response Date*				
onsemi													2024-04-25			
Contact Name				Title - Contac	Title - Contact			Phone - Contact*				Email - Contact*				
Product-E	Product-Env-Stewards P				Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative* Title -				Citle - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards				Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item			Number Mfr Item Name				Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type		
	FT7522I			7.5s Reset Timer				2024-04-25		TH2		2.0707	mg	Each		
Manufacturing Process Information																
	Terminal Plating / Grid Array Material Te				Germinal Base Alloy J-STD-020 MSI			ng Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles					
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1				260 C 30		seconds 3						
Comments																
level 1 - maximum time at peak temperature during soldering is 10-30 seconds																
For more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.1165	mg	Supplier	Silicon (Si)	7440-21-3		0.1165	mg
Die Attach Epoxy	0.0146	mg		Epoxy resin	proprietary data		0.0095	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0051	mg
Lead Frame	0.7075	_	Supplier	Magnesium (Mg)	7439-95-4		0.0011	mg
			Supplier	Silicon (Si)	7440-21-3		0.0046	mg
			В	Nickel (Ni)	7440-02-0		0.0212	mg
			Supplier	Copper (Cu)	7440-50-8		0.6806	mg
Mold Compound-Black	1.21	mg	Supplier	Carbon Black (C)	1333-86-4		0.006	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1.0648	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.0786	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0605	mg
Plating	0.0099		Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			В	Nickel (Ni)	7440-02-0		0.0091	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
Wire Bond - Au	0.0122	mg	Supplier	Gold (Au)	7440-57-5		0.0122	mg